



Welcome to the Techni-Tool Family!

We're proud to welcome Indium Corporation to our industry-leading roster of electronic production manufacturers. For over 70 years Indium has been an innovative producer of solder paste, wire, bar, solder flux and more, and now all are available through Techni-Tool.

SOLDER PASTE

Indium3.2 Pb-Free Water-Soluble Solder Paste

An air or nitrogen reflow, water-soluble solder paste specifically formulated to accommodate the higher processing temperatures required by Sn/Ag/Cu, Sn/Ag and Sn/Sb Pb-Free alloy systems. Consistent fine-pitch printing performance, wide reflow profile window, excellent response-to-pause printing performance.

TT No.	Alloy	Metal	Powder Size	Packaging
881S0321	SAC305	88.5%	Type 3	500g jar
881S0322	SAC305	88.5%	Type 3	600g cartridge

Indium6.3 Water-Soluble Solder Paste

Excellent wetting, solder joint appearance, printing and response to pause. Wide reflow profile window and good slump resistance. Low voiding, halogen-free.

TT No.	Alloy	Metal	Powder Size	Packaging
881S0631	Sn63 Pb37	89.5%	Type 3	500g jar
881S0632	Sn63 Pb37	89.5%	Type 3	600g cartridge

Indium8.9HF Pb-Free Solder Paste

Air reflow, no-clean solder paste that's halogen-free per EN14582 test method. High transfer efficiency through small apertures. Eliminates hot and cold slump. High oxidation resistance. Wets well to oxidized BGA and pad surfaces. High probe testability which minimizes false failures in ICT.

TT No.	Alloy	Metal	Powder Size	Packaging
881S0893	SAC305	88.5%	Type 3	500g jar
881S0894	SAC305	88.5%	Type 3	600g cartridge



Indium8.9 Pb-Free Solder Paste

Air reflow, no-clean solder paste delivers high transfer efficiency through small apertures. High oxidation resistance virtually eliminates incomplete coalescence of small deposits. Low voiding in BGA/CSP solder joints.

TT No.	Alloy	Metal	Powder Size	Packaging
881S0895	SAC305	88.75%	Type 3	500g jar
881S0896	SAC305	88.75%	Type 3	600g cartridge

NC-SMQ®92J Solder Paste

Halide-free, air reflow, no-clean solder paste formulated to leave a benign, easily-penetrated residue which won't clog multi-point probes. Ideal for high speed surface mount lines utilizing fast print speeds and rapid chip placement. Consistent fine-pitch paste deposition, unsurpassed stencil life and tack time, excellent wetting.

TT No.	Alloy	Metal	Powder Size	Packaging
881S0921	Sn63 Pb37	90.25%	Type 3	500g jar
881S0922	Sn63 Pb37	90.25%	Type 3	600g cartridge

Indium Also Specializes In Type 4 Solder Paste - Call For More Details!

SOLDER WIRE AND BAR



CW-201 RA Cored Wire Solder

Highly reliable, compatible with Pb-Free and Sn/Pb materials. Provides excellent solder spread with minimal smoking, spatter and odor. Fast wetting speed minimizes rework cycle time.



TT No.	Alloy	Diameter	Size
881S0211	Sn63 Pb37	.020"	1 lb. spool
881S0212	Sn63 Pb37	.032"	1 lb. spool
881S0213	SAC305	.020"	1 lb. spool
881S0214	SAC305	.032"	1 lb. spool

CW-301 Water-Soluble Cored Wire Solder

Same features as CW-201, plus cleans easily with cold water.

TT No.	Alloy	Diameter	Size
881S0311	Sn63 Pb37	.020"	1 lb. spool
881S0312	Sn63 Pb37	.032"	1 lb. spool
881S0313	SAC305	.020"	1 lb. spool
881S0314	SAC305	.032"	1 lb. spool

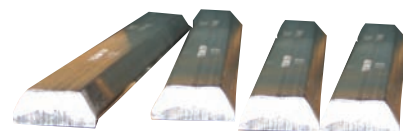
Ultra-Clear 807 Flux-Cored Wire

Same features as CW-201, but made with ultra-clear modified rosins. Contains no brominated fire retardants or REACH substances of very high concern. Contains a small amount of halogen but meets IPC J-709 requirements for halogen-free assembly.

TT No.	Alloy	Diameter	Size
881S0871	Sn63 Pb37	.020"	1 lb. spool
881S0872	Sn63 Pb37	.032"	1 lb. spool
881S0873	SAC305	.020"	1 lb. spool
881S0874	SAC305	.032"	1 lb. spool



Sold in 25 lb. boxes which contain 15 bars.



Most common lead-free bar. SAC305 (96.5Sn/3Ag/0.5Cu).

No. 881S0305

Low-cost lead-free bar. Sn995 (99.5Sn/0.5Cu+Co).

No. 881S0995

Standard tin/lead bar. 63Sn/37Pb.

No. 881S0337

NO-CLEAN WAVE SOLDER FLUX

WF-7745 VOC & Halogen-Free No-Clean Flux

Water-based flux designed for wave soldering and selective soldering of through-hole, bottom-side surface mount and mixed-technology boards. Performs well with both Pb-free and Sn/Pb solders and processes. VOC and halogen-free. Non-flammable properties eliminate the need for special storage. One gallon.

No. 881CH745

WF-9940 No-Clean Flux

Highly active, very heat stable flux for through-hole and mixed-technology assemblies. Performs well with both tin/lead and lead-free solders. Passes all known reliability requirements even with high degree of activation. Non-corrosive. One gallon.

No. 881CH940

WF-7742 VOC-free Flux

No-clean flux specifically developed for Pb-free wave soldering of surface-mount, mixed-technology and through-hole electronics assemblies. Water-based, non-flammable formulation dramatically reduces VOC emissions and eliminates special storage requirements. Wide process window provides excellent solderability on difficult to solder assemblies and reduces solder balling. One gallon.

No. 881CH742

WF-9945 Halogen-Free Flux

Provides excellent wetting and hole-fill for through-hole and mixed-technology assemblies. Can be used with tin/copper, tin/silver/copper and tin/lead alloys. One gallon.

No. 881CH945



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